



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2022-01-25
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	giovanni giacopello	<b>Representative Title</b>	ADG Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS2L60ZFY	BX7Z*Z24QD5U	A	996I	2022-01-25
Amount	UoM	Unit type	ST ECOPACK Grade	
13	mg	Each	ECOPACK 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00286778	

Package Designator	Package Size	Nbr of instances	Shape	
CHP	2.60,1.60,0.98	2	flat	
Comment	SOD123-FLAT NEP			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Exemption id.	Description
8e	8e - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 19th March 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die	560
Lead	0.37	soft solder	29520

QueryList : REACH-8th July 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	0.37	Soft solder	29520
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	0.37	Soft solder	946154

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present in the component :	Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BX7Z*224QDSU									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	0.490	mg	supplier	die	Silicon(Si)	7440-21-3		0.457	mg	932653	36560				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.004	mg	8163	320				
				supplier	metallisation	Gold(Au)	7440-57-5		0.004	mg	8163	320				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.007	mg	14286	560				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	2041	80				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	2041	80				
				supplier	passivation	Silicon oxide	7631-86-9		0.004	mg	8163	320				
				supplier	polymer coating	Durimide	proprietary		0.012	mg	24490	960				
				Leadframe & clip	M-004 Copper and its alloys	6.235	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.227	mg	998717	498160
								supplier	alloy	Iron (Fe)	7439-89-6		0.006	mg	962	480
supplier	alloy	Phosphorus (P)	7723-14-0						0.002	mg	321	160				
Soft solder	Solder	0.390	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	0.369	mg	946154	29520				
				supplier	solder	Tin(Sn)	7440-31-5		0.019	mg	48718	1520				
				supplier	solder	Flux residue	proprietary		0.002	mg	5128	160				
Encapsulation	M-011 Other inorganic materials	5.218	mg	supplier	mold compound	Silica vitreous	60676-86-0		3.653	mg	700076	292240				
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		0.762	mg	146033	60960				
				supplier	mold compound	Phenol resin	9003-35-4		0.417	mg	79916	33360				
				supplier	mold compound	Aluminium hydroxide	21645-51-2		0.365	mg	69950	29200				
				supplier	mold compound	Carbon black	1333-86-4		0.021	mg	4025	1680				
Connections coating	Solder	0.167	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.167	mg	1000000	13360				